WHAT IS CLAIMED IS:

1. A bonding device, comprising:

a plurality of laser oscillators that oscillate laser beams;

a plurality of guide beam parts that guide the laser beams oscillated from the laser oscillators;

a bonding tool that is irradiated and heated by the laser beams guided from the guide beam parts so that an electronic part held on the bonding tool is heated by the laser beams and is bonded to a base plate, wherein

the bonding tool is segmented into a plurality of heat regions,

each of the heat regions is irradiated by the laser beams that are guided through the guide beam parts so that some of the heat regions are heated at a temperature different from other heat regions,

the electronic part is in a polygon shape having a plurality of corners,

the heat regions are segmented into corner regions, outer regions and inner regions, the corner regions that correspond to the corners, the outer regions that are at an outer side and other than the corner regions, and the inner regions that are at an inner side, and

laser outputs of the laser oscillators for the inner regions, the outer regions and the corner regions are set to satisfy that

the laser output for the inner regions is smaller than that for the outer regions, and

the laser output for the outer regions is smaller than that for the corner regions, and

an insulation part is disposed at a middle section between two of the heat regions, the insulation part suppressing a heat transfer between the heat regions.

2. The bonding device of claim 1, wherein

the insulation part is shaped as a groove formed on the bonding tool.

3. The bonding device of claim 2, wherein

the bonding tool has a chip suck path that is a hole through which a negative

pressure is imported so that the electronic part is sucked and held by the negative pressure on the bonding tool, and

when the electronic part is sucked on the bonding tool, the groove as the insulation part becomes airtight by the electronic part, and is communicatively connected to the chip suck path.

4. The bonding device of claim 1, wherein

the heat regions are further segmented into corner adjacent regions that surround the corner regions,

laser output of the laser oscillators for the corner adjacent regions is set to be above the laser output for the outer regions and below the laser output for the corner regions.